

REMARKS

Reconsideration and allowance of this application are respectfully requested.

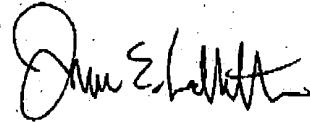
New claims 14-29 are similar to allowed claim 31 of the parent application but have been clarified and broadened. Claim 14 is broader and makes it clear that the claim covers embodiments wherein the sealing resin does not seal the entire upper region of the outer lead portions as well as embodiments wherein the sealing resin does seal the entire upper region of the outer lead portions. Claim 14 recites that the sealing resin does seal the groove portion, and that the outer peripheral region of the chip includes a region of the thin metal wires but may or may not include a lower region of the die pad (this feature is covered in dependent claim 16). Also, claim 14 is broader in that it omits recitation of the lead frame while more broadly reciting lead portions and recites that the chip is mounted over the die pad (i.e., it need not contact or touch the die pad as e.g. an adhesive layer may be interposed therebetween). Further, the feature wherein the die pad is disposed higher than the upper surface of the inner lead portions is covered in claim 16. Claim 22 is similar to new claim 14 but is simplified particularly with respect to the "leads."

For at least the reasons presented in the Responses filed in the parent application, it is respectfully submitted that pending

claims 11-29 are directed to allowable subject matter. A Notice of Allowance is respectfully solicited.

If any issues remain which may be best resolved through a telephone communication, the Examiner is requested to kindly telephone the undersigned at the local, Washington D.C. telephone number listed below.

Respectfully submitted,



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